222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE  BOARD #: TIDA-01566  REVISION: E1  SVN REV: Not In VersionControl
TID #: TIDA-01566

PLOT NAME = Top Assembly Drawing  GENERATED: 1/19/2018 10:06:59 AM  TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

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PLOT NAME = Bottom Assembly Drawing

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